RICOH

R1516x SERIES

150mA 36V Input LDO Regulator

NO.EA-258-111025

OUTLINE

The R1516x Series are CMOS-based high-voltage resistant and low supply current voltage regulator ICs that provide the minimum 150mA of output voltage. Internally, the R1516x Series consists of a Foldback Protection Circuit, and a Thermal Shutdown Circuit in addition to the basic regulator circuits. The operating temperature range is between -40°C to 105°C, and the maximum input voltage is 36V. All these features allow the R1516x Series to become an ideal power source of electric home appliances.

The R1516x Series are available in fixed output voltage options between 1.8V and 6.2V in 0.1V steps. The output voltage accuracy is ±1%.

The R1516x Series are available in two types of packages: SOT-89-5 that is for high-density mounting and HSOP-6J that is for high wattage.

FEATURES

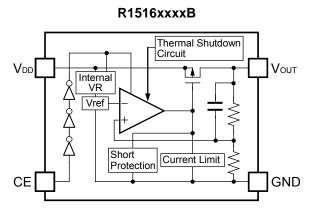
- Input Voltage Range
 4V to 36V
- Supply Current Typ. 29µA
- Standby Current Typ. 0.1µA
- Output Voltage Temperature Coefficient Typ. ±100ppm/°C
- Output Current Min. 150mA (Vout=5.0V, VIN=8.0V)
- Line Regulation Typ. 0.1%/V
- Output Voltage Accuracy.....±1% (Vout ≥ 3.2V, Topt=25°C)
- Packages ······ SOT-89-5, HSOP-6J
- Output Voltage Range 1.8V to 6.2V (0.1V steps)
- (For other voltages, please refer to MARK INFORMATIONS.)
- Built-in Foldback Protection Circuit 50mA (Current at short mode)

APPLICATIONS

- Power source for home appliances such as refrigerators, rice cookers, electric hot-water pot.
- Power source for notebook PCs, digital TVs, cordless phones, and private LAN system.
- Power source for office equipment machines such as copiers, printers, facsimiles, scanners, projectors.

R1516x

BLOCK DIAGRAMS

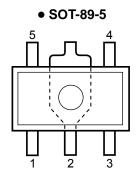


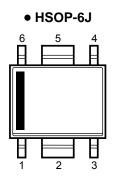
SELECTION GUIDE

The output voltage and the package for the ICs can be selected at the user's request.

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
R1516HxxxB-T1-FE	SOT-89-5	1,000pcs	Yes	Yes
R1516SxxxB-E2-FE	B-E2-FE HSOP-6J 1,000pcs Yes		Yes	
xxx : The output voltage can be designated in the range of 1.8V(018)to 6.2V(062)in 0.1V steps. (For other voltages, please refer to MARK INFORMATIONS.)				

PIN CONFIGURATIONS





PIN DESCRIPTIONS

• SOT-89-5

Pin No.	Symbol	Description	
1	Vout	Output Pin	
2	GND [*]	Ground Pin	
3	CE	Chip Enable Pin ("H" Active)	
4	GND [*]	Ground Pin	
5	Vdd	Input Pin	

*) The GND pin must be wired together when it is mounted on board.

• HSOP-6J

Pin No.	Symbol	Description	
1	Vout	Output Pin	
2	GND [*]	Ground Pin	
3	CE	Chip Enable Pin ("H" Active)	
4	GND [*]	Ground Pin	
5	GND [*]	Ground Pin	
6	Vdd	Input Pin	

*) The GND pin must be wired together when it is mounted on board.

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating	Unit	
Vin	Input Voltage	-0.3~50	V	
Vin	Peak Input Voltage*1	60	V	
VCE	Input Voltage (CE Pin)	-0.3∼Vı⊳+0.3≦50	V	
Vout	Output Voltage	_0.3~Vıℕ+0.3≦50	V	
Ιουτ	Output Current	250	mA	
PD	Power Dissipation (SOT-89-5) ^{*2}	900	mW	
	Power Dissipation (HSOP-6J)*2	1700		
Topt	Operating Temperature Range	-40 to +105	°C	
Tstg	Storage Temperature Range	–55 to +125	°C	

*1) Duration time: 200ms

*2) For Power Dissipation, please refer to PACKAGE INFORMATION.

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

ELECTRICAL CHARACTERISTICS

The specifications in \square are applicable under the condition of -40°C \leq Topt \leq 105°C.

R1516xxxxB

Topt=25°C

Symbol	Item	Conditions		Min.	Тур.	Max.	Unit	
VIN	Input Voltage			4		36	V	
lss	Supply Current	VIN=VOUT+3.	.0V, I	lout= 0mA		29	45	μA
Istandby	Standby Current	VIN=36V, Vo	CE=0\	/		0.1	1.0	μA
Vout	Output Voltage	Vin=Vout+3.0V, Iout=1mA		Vouт ≥ 3.2V	×0.99 ×0.98		×1.01 ×1.02	V
VOUT				Vout < 3.2V	×0.985 ×0.975		×1.015 ×1.025	
Ιουτ	Output Current	F	Pleas	e refer to "Output	Current by	y Output \	/oltage".	
ΔV out/ ΔI out	Load Regulation	P	lease	e refer to "Load Re	egulation b	by Output	Voltage".	
ΔVout/ΔVin	Line Regulation	Iout=1mA	(Vo	$f+1.5V \le V_{IN} \le 36V,$ ut $\ge 2.5V)$ $\le V_{IN} \le 36V,$	-	0.1	0.7	%/V
	Dranout Voltage	(Voi		ut < 2.5V)			Voltaga"	
VDIF	Dropout Voltage			e refer to "Dropout	t voltage t	by Output	voltage.	
ΔV оυт/ ΔT opt	Output Voltage Temperature Coefficient	$\label{eq:VIN} \begin{split} V_{\text{IN}} = & V_{\text{OUT}} + 3.0V, \ I_{\text{OUT}} = 1mA \\ -& 40^{\circ}C \leq T_{\text{Opt}} \leq 105^{\circ}C \end{split}$			±100		ppm/°C	
lsc	Short Current Limit	Vout=0V			50		mA	
Vсен	CE Input Voltage "H"			1.3		Vin	V	
VCEL	CE Input Voltage "L"			0		0.35	V	
TTSD	Thermal Shutdown Temparature	Junction Temeprature			150		°C	
Ttsr	Thermal Shutdown Released Temparature	Junction Temeprature			125		°C	

• Output Current by Output Voltage

Topt=25°C

Topt=25°C

Output Voltage	Output Current Iout (mA)		
V оит (V)	Condition	Min.	
$1.8 \le V_{\text{OUT}} < 3.0$	VIN=VOUT+5.0V		
$3.0 \le V_{\text{OUT}} < 5.0$	VIN=VOUT+4.0V	150	
$5.0 \leq V_{\text{OUT}} \leq 6.2$	VIN=VOUT+3.0V		

• Load Regulation by Output Voltage

Load Regulation (mV) **Output Voltage** Vout (V) Condition Max. Тур. $1.8 \le V_{\text{OUT}} \le 3.0$ 30 (Vout=3.0V) 70 VIN=VOUT+3.0V 105 $3.0 < V_{\text{OUT}} \leq 5.0$ 40 (Vout=5.0V) $1mA \leq I_{\text{OUT}} \leq 40mA$ $5.0 < V_{\text{OUT}} \le 6.2$ 50 (Vout=6.2V) 125

R1516x

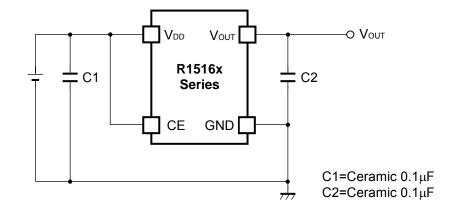
• Dropout Voltage by Output Voltage

⊤=20mA) utput Voltage	Topt=25 Dropout Voltage
Vout (V)	V₀⊧ (V) Max.
Vout=1.8	2.30
Vout=1.9	2.20
Vout= 1.0	2.10
Vout=2.0	2.00
Vout=2.2	1.90
Vout=2.2	1.80
Vout=2.4	1.70
Vout=2.5	1.60
Vout=2.6	1.50
Vout=2.7	1.40
Vout=2.8	1.30
Vout=2.9	1.20
Vout=3.0	1.10
Vоит= 3 .1	1.06
Vout=3.2	1.02
Vout=3.3	0.98
Vout=3.4	0.94
Vout=3.5	0.90
Vout=3.6	0.86
Vout=3.7	0.82
Vout=3.8	0.78
Vout=3.9	0.74
Vout=4.0	0.70
Vout=4.1	0.69
Vout=4.2	0.68
Vout=4.3	0.67
Vout=4.4	0.66
Vout=4.5	0.65
Vout=4.6	0.64
Vout=4.7	0.63
Vout=4.8	0.62
Vout=4.9	0.61
$0 \le V$ out ≤ 6.2	0.60

RECOMMENDED OPERATING CONDITIONS (ELECTRICAL CHARACTERISTICS)

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

TYPICAL APPLICATION



TECHNICAL NOTES

When using the R1516x Series, please consider the following points.

Phase Compensation

The R1516x Series provide the constant-voltage without using C1 and C2 capacitors. However, if the input line is too long, C1 should be connected. To minimize the input voltage fluctuation and the transient output voltage fluctuation that is caused by the load fluctuation, C2 size should be increased. Please refer to the Basic Test Circuit below when connecting a 0.1μ F to 20μ F C1 capacitor from V_{DD} to GND, and also connecting a 0.1μ F to 20μ F C2 capacitors, V_{DD}, GND and V_{OUT} should be connected as close as possible to each other.

GND Wiring on Boards

For SOT-89-5 package, please connect the No.2 pin and the No.4 pin to the ground plane on the board.

For HSOP-6J package, please connect the No.2 pin, the No.4 pin and the No.5 pin to the ground plane on the board.

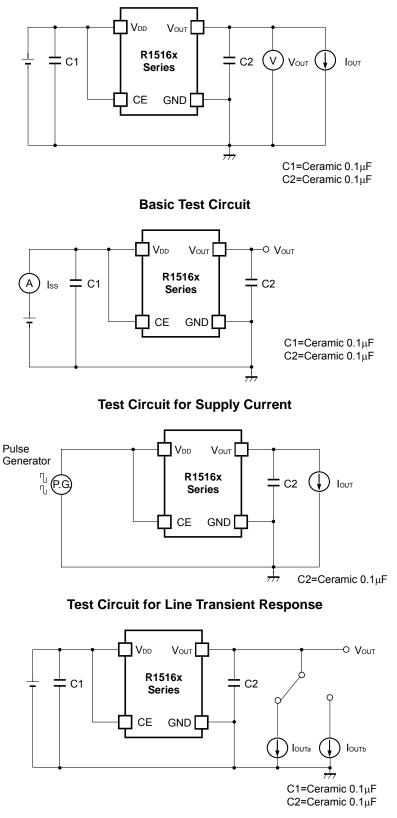
Thermal Shutdown

The thermal shutdown is included, which limits the junction temperature to a maximum 150°C (Typ.). Under extreme conditions when the junction temperature begins to rise above 150°C, the output is turned off, reducing the output current to zero. When the junction temperature drops below +125°C (Typ.), the output is turned on again and the output current is restored to its nominal value. The output repeats turning on and off to form a pulse shaped output unless the causes of the temperature rise are removed.

Chip Enable (CE) Circuit

The electrical potential level of chip enable (CE) pin should not be set in between V_{CEH} and V_{CEL} . Using the electrical potentials in between V_{CEH} and V_{CEL} may cause the increase of supply current and may result in unstable output.

TEST CIRCUITS

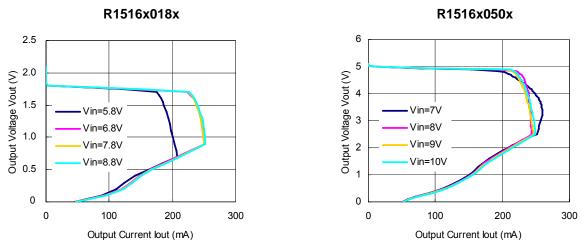


Test Circuit for Load Transient Response

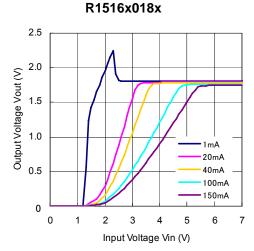
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Typical Characteristics

1) Output Voltage vs. Output Current (C1=0.1µF, C2=0.1µF, Topt=25°C)



2) Output Voltage vs. Input Voltage (C1=0.1µF, C2=0.1µF, Topt=25°C) R1516x050x



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4.5

Dropont Voltage Vdif (</br>

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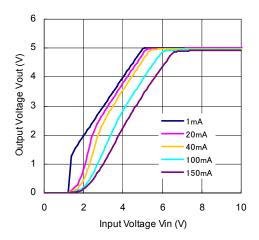
25

50

75

Output Current lout (mA)

100



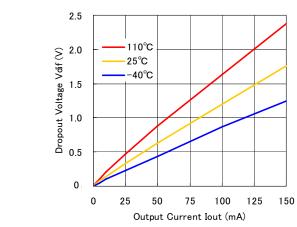


110°C 25°C

-40°C

150

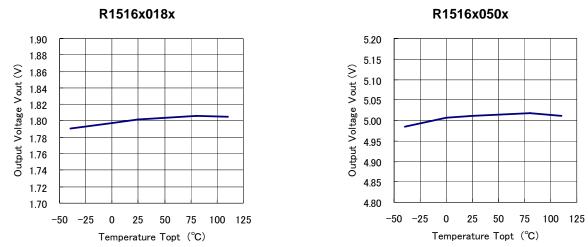
125



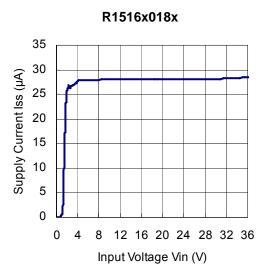
R1516x050x

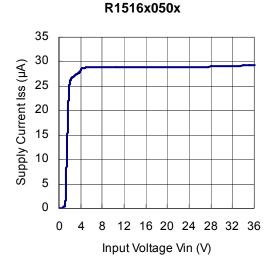
R1516x

4) Output Voltage vs. Temperature (C1=0.1 μ F, C2=0.1 μ F)

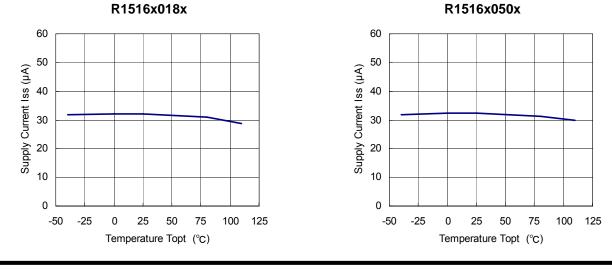




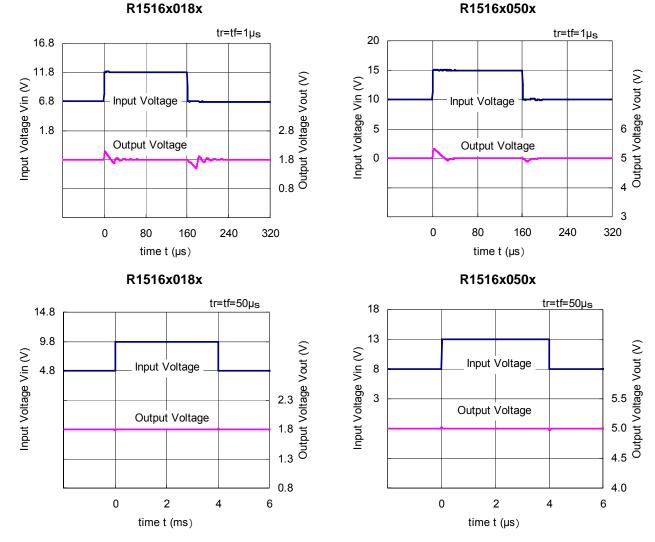






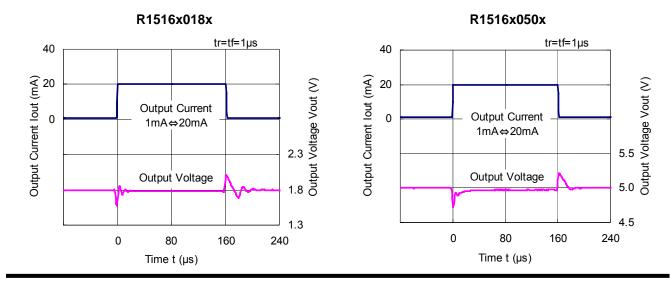


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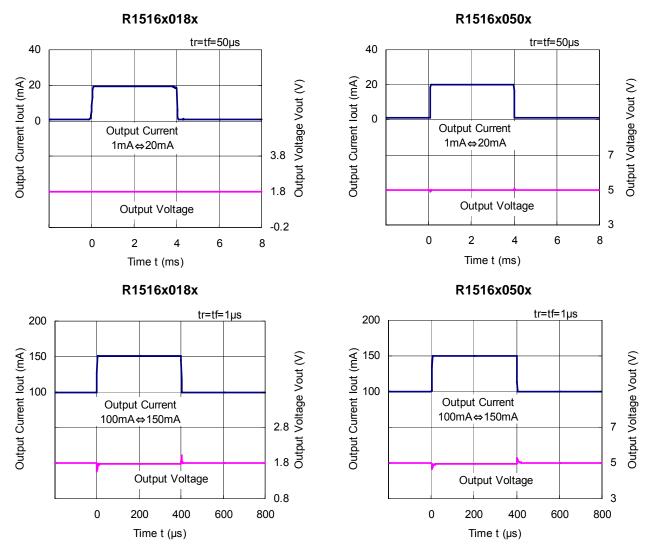


7) Input Transient Response (C1=none, C2=Ceramic 0.1µF, IouT=1mA, Topt=25°C)

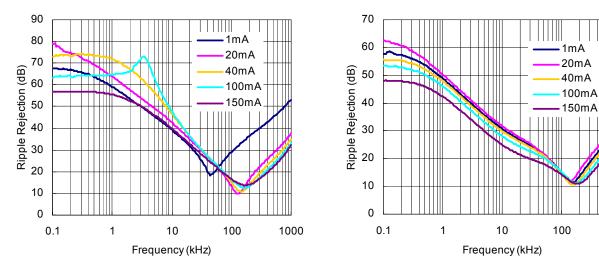
8) Load Transient Response (C₁=Ceramic 0.1µF, C₂=Ceramic 0.1µF, Topt=25°C)



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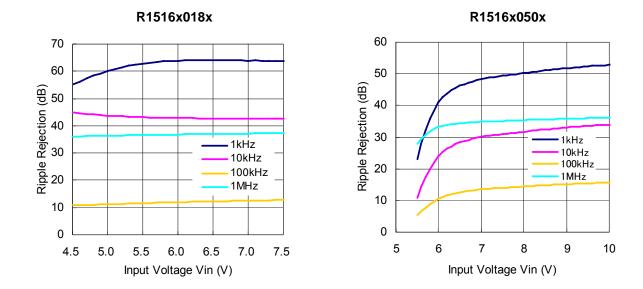
9) Ripple Rejection vs. Frequency (C1=none, C2=Ceramic 0.1µF, Ripple=0.5Vp-p, Topt=25°C)



R1516x018x

R1516x050x

1000



10) Ripple Rejection vs. Input Voltage (C1=none, C2=Ceramic 0.1µF, Iour=20mA, Ripple=0.5Vp-p, Topt=25°C)

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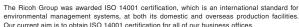
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Ricoh presented with the Japan Management Quality Award for 1999. Ricoh continually strives to promote customer satisfaction, and shares the achievements of its management quality improvement program with people and society.



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Ricoh completed the organization of the Lead-free production for all of our products. After Apr. 1, 2006, we will ship out the lead free products only. Thus, all products that will be shipped from now on comply with RoHS Directive.

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